DBZ 3

GENERIC PACKAGE VIEW

SOT-23 - 1.12 mm max height SMALL OUTLINE TRANSISTOR



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



4203227/C

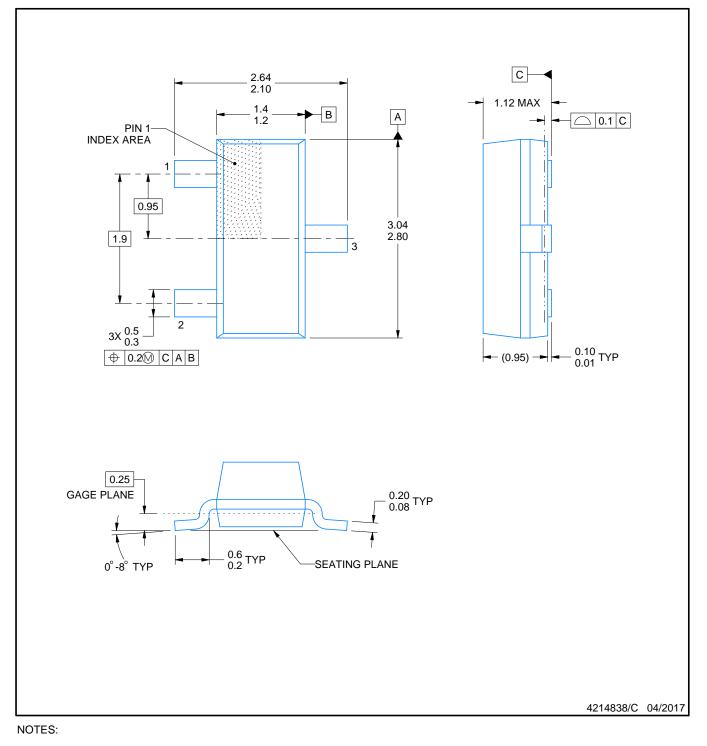
DBZ0003A



PACKAGE OUTLINE

SOT-23 - 1.12 mm max height

SMALL OUTLINE TRANSISTOR



All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
This drawing is subject to change without notice.
Reference JEDEC registration TO-236, except minimum foot length.



DBZ0003A

EXAMPLE BOARD LAYOUT

SOT-23 - 1.12 mm max height

SMALL OUTLINE TRANSISTOR



NOTES: (continued)

4. Publication IPC-7351 may have alternate designs.5. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

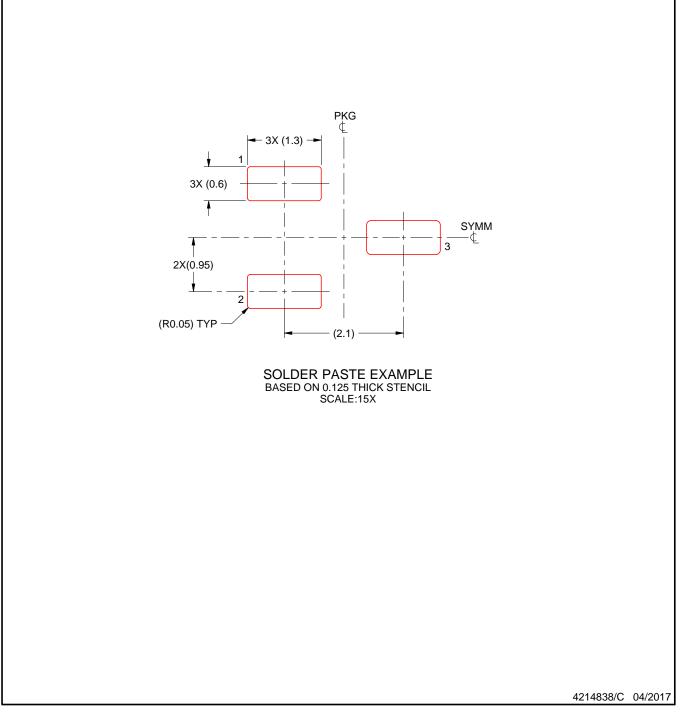


DBZ0003A

EXAMPLE STENCIL DESIGN

SOT-23 - 1.12 mm max height

SMALL OUTLINE TRANSISTOR



NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

7. Board assembly site may have different recommendations for stencil design.



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